WHAT IS CLAIMED IS:

1. A package for a semiconductor device comprising:

a semiconductor die having a laterally conducting structure and a ground contact on an upper surface; and

a leadframe comprising,

a diepad in contact with a lower surface of the die,

a lead separated from the diepad, and

a supplemental downbond diepad portion projecting from a main portion of the diepad and configured to receive a downbond wire from the ground contact.

2. The package of claim 1 wherein the supplemental diepad portion is positioned on an end of the package between the lead and a second lead that is also separate from the diepad.

3. The package of claim 1 further comprising a second lead projecting from the diepad.

4. The package of claim 3 wherein the supplemental diepad portion comprises a part of the second lead.

5. The package of claim 1 comprising more than one supplemental downbond portion.

6. The package of claim 1 wherein the die comprises a power IC die.

7. The package of claim 1 wherein the die is configured to operate with a current of between about 1 and 20 Amps.

8. The package of claim 1 wherein the die is selected from the group consisting of an integrated circuit, a JFET, and a lateral MOSFET.

9. The package of claim 1 wherein the diepad comprises copper.

10. A method of packaging a laterally conducting semiconductor die, the method comprising providing a supplemental diepad portion to receive a downbond wire

from a ground contact on an upper surface of the die, such that area of a main portion of the diepad need not be allocated to receive the downbond wire and can instead be occupied by the laterally conducting die.

11. The method of claim 10 wherein the supplemental diepad portion is provided on an end of the package between two leads separate from the diepad.

12. The method of claim 10 wherein the supplemental diepad portion is provided on a side of the package as a part of a lead projecting from the diepad.

13. The method of claim 10 wherein the leadframe supports a power IC die.

14. The method of claim 10 further comprising providing more than one supplemental diepad portion.

15. The method of claim 10 wherein the leadframe supports a die operated with a current of between about 1 to 20 Amps.

16. The method of claim 10 wherein the leadframe supports a die selected from the group consisting of an IC, a lateral MOSFET, and a JFET.